

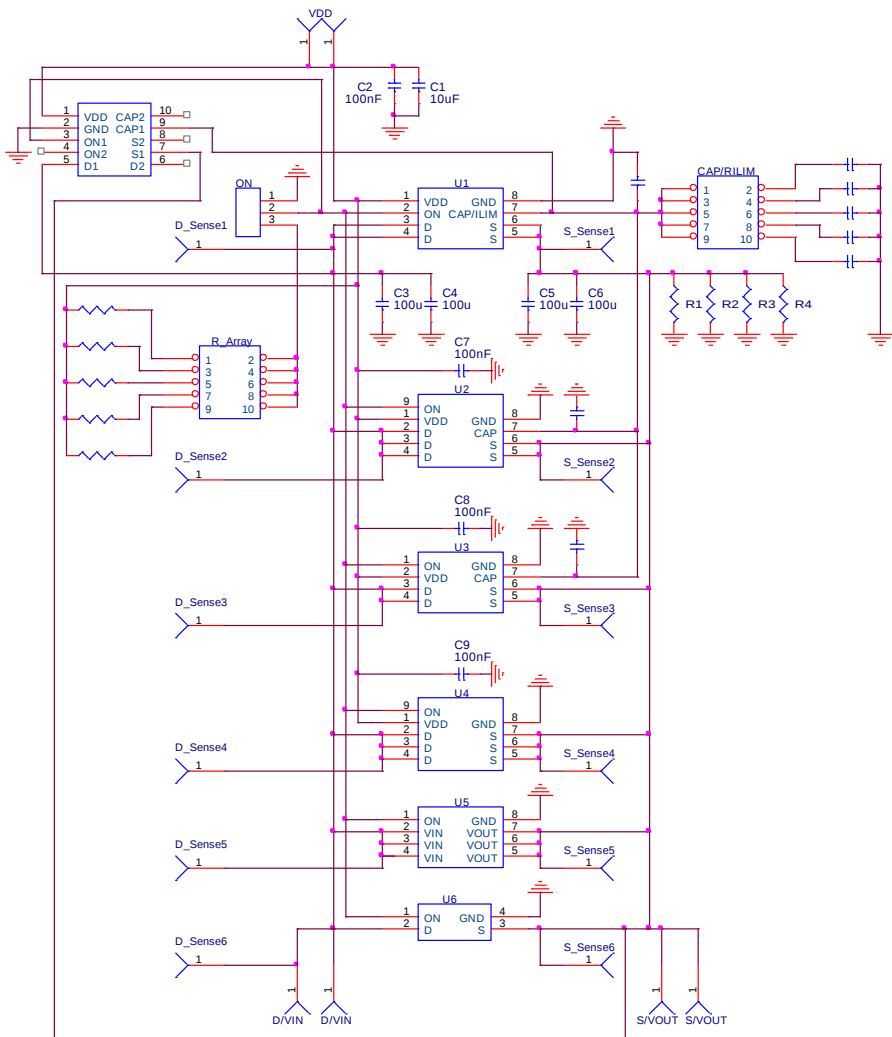


Figure 4. SLG59M1470V Connection Circuit



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Description

The SLG59M1470V is a $9.8 \text{ m}\Omega$, $\sim 6 \text{ A}$ single-channel load switch that is able to switch 1.0 to 3.3 V power rails. The product is packaged in an ultra-small $1.5 \times 2 \text{ mm}$ package.

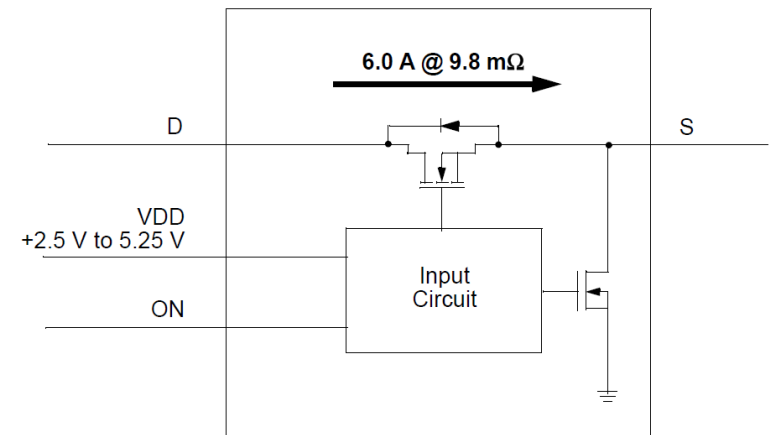


Figure 1: SLG59M1470V Block Diagram

This layout guide provides some important information about the PCB layout of SLG59M1470V applications.

SILEGO FC-TDFN 1.5x2-9L PKG

Unit: um

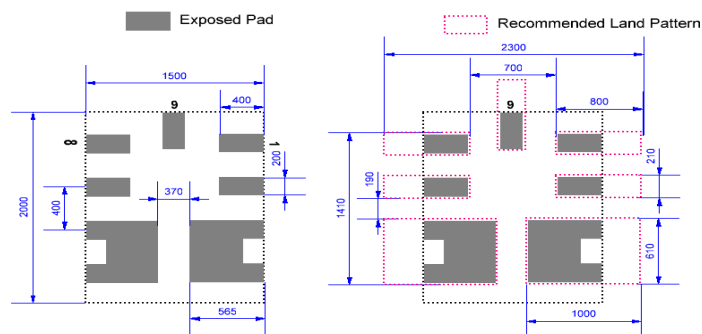


Figure 2. SLG59M1470V Package Dimensions and Recommended Land Pattern

Please solder your SLG59M1470V here

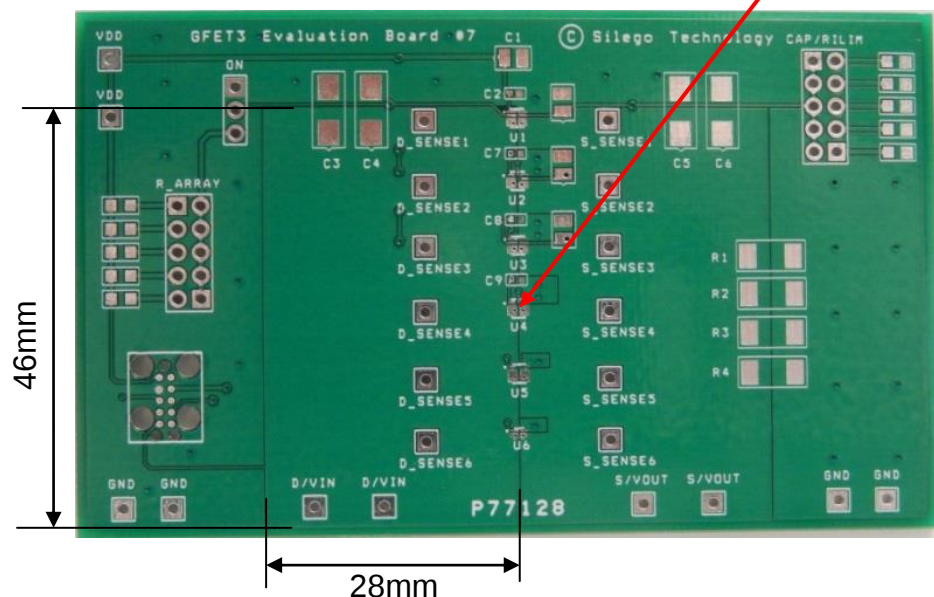


Figure 3. SLG59M1470V Evaluation Test Board

Note: Evaluation board has D_Sense and S_Sense pads. Please use them only for RDS(ON) evaluation.

2. Power and Ground Planes

- 2.1. The VDD pin needs are 0.1uF and 10uF external capacitors to smooth pulses from the power supply. Locate these capacitors close to PIN1.
- 2.2. The trace length from the control IC to the ON pin should be as short as possible and must avoid crossing this trace with power rails.
- 2.3. The D/VIN and S/VOUT pins carry significant current. Please note how the D/VIN and S/VOUT pads are placed directly on the power planes in Figure 3, which minimizes the $R_{ds(ON)}$ associated with long, narrow traces. The D/VIN, S/VOUT and GND pins dissipate most of the heat generated during high-load current condition. The layout shown in Figure 3 is illustrating a proper solution for heat to transfer as efficiently as possible out of the device.
- 2.4. The GND pin (PIN8) should be connected to GND.
- 2.5. 2 oz. copper is recommended for higher currents.